CMDFSHC3-100

SURFACE MOUNT SILICON 3.0 AMP SCHOTTKY RECTIFIER





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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMDFSHC3-100 is a 3.0 Amp silicon Schottky rectifier mounted in a durable epoxy surface mount case, utilizing glass passivated chips.

MARKING CODE: C3-100C

MAXIMUM RATINGS: (T_A=25°C unless otherwise noted)

| | SYMBOL | | UNITS |
|-------------------------------------|------------------------|-------------|-------|
| Peak Repetitive Reverse Voltage | V _{RRM} | 100 | V |
| DC Blocking Voltage | V _R | 100 | V |
| Average Forward Current | Ι _Ο | 3.0 | А |
| Peak Forward Surge Current (8.3ms) | IFSM | 100 | А |
| Operating Junction Temperature | Т _Ј | -55 to +125 | °C |
| Storage Temperature | T _{stg} | -55 to +150 | °C |
| Typical Thermal Resistance (Note 1) | Θ_{JA} | 55 | °C/W |
| Typical Thermal Resistance (Note 1) | Θ _{JL} | 17 | °C/W |
| FLECTRICAL CHARACTERISTICS: (TA=25) | °C unless otherwise no | oted) | |

| SYMBOL | TEST CONDITIONS | TYP | MAX | UNITS |
|----------------|--------------------------------|------|------|-------|
| IR | V _R =100V | | 500 | μΑ |
| V _F | I _F =3.0A (Note 2) | 0.78 | 0.85 | V |
| СЈ | V _R =4.0V, f=1.0MHz | 180 | | pF |

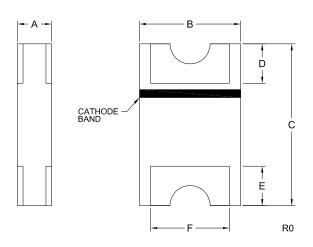
Notes: 1) FR-4 Epoxy PC Board with copper mounting pad area of $5.0 mm^2$ 2) Pulse test tp=300 $\mu s,$ Duty Cycle=1%

R2 (27-January 2021)



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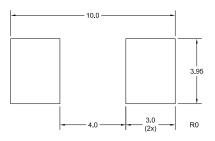


SMC DFN CASE - MECHANICAL OUTLINE

| DIMENSIONS | | | | | | | |
|-------------------|--------|-------|-------------|------|--|--|--|
| | INCHES | | MILLIMETERS | | | | |
| SYMBOL | MIN | MAX | MIN | MAX | | | |
| А | 0.037 | 0.049 | 0.95 | 1.25 | | | |
| В | 0.193 | 0.201 | 4.90 | 5.10 | | | |
| С | 0.311 | 0.319 | 7.90 | 8.10 | | | |
| D | 0.073 | 0.081 | 1.85 | 2.05 | | | |
| E | 0.073 | 0.081 | 1.85 | 2.05 | | | |
| F | 0.154 | | 3. | 90 | | | |
| SMC DEN (REV: R0) | | | | | | | |

SMC DFN (REV: R0)

SUGGESTED MOUNTING PADS (Dimensions in mm)



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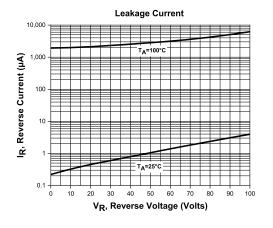
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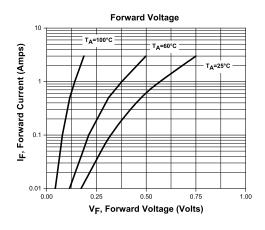


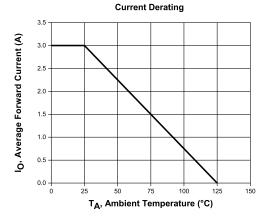


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TYPICAL APPLICATIONS

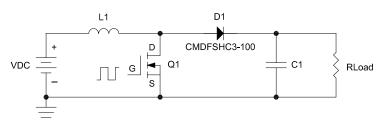


Figure 1. Boost Converter: One of the most traditional uses of the Schottky rectifier is in the boost converter, which requires a low-loss rectification element. The CMDFSH Series has been designed to highlight the main qualities of Schottky rectifiers in a space-efficient package; including a low forward voltage drop, fast turn-on time, and extremely fast recovery time. These attributes make the CMDFSH Series an excellent boost rectifier choice for any boost converter system.

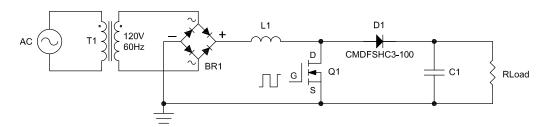


Figure 2. PFC Boost Converter: The most popular adaption of the boost converter is the power factor correction (PFC) boost converter. The power factor is the ratio of real power to actual power dissipated in a circuit. The actual power dissipation of a circuit is altered when inductive components are used in a design. This is due to the inductive reactance of the coil, which causes the current flowing through the system to lag behind the voltage in the system, causing the signals to fall out of phase. Power factor correction increases the power factor by using capacitance to create a leading current effect that compensates for the lagging current effect that is caused by the inductor.

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OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- · Environmental regulation compliance
- Customer specific screening
- · Up-screening capabilities

· Custom product packing

Custom bar coding for shipments

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when 1. ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

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